# INTEGRATED CIRCUITS

# DATA SHEET

**74F139**Dual 1-of-4 decoder/demultiplexer

Product specification

1990 Feb 23

IC15 Data Handbook





74F139

#### **FEATURES**

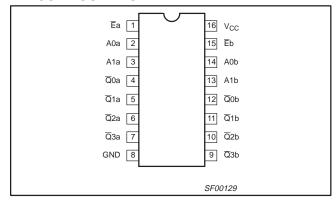
- Demultiplexing capability
- Two independent 1-of-4 decoders
- Multifunction capability

#### **DESCRIPTION**

The 74F139 is a high speed, dual 1-of-4 decoder/demultiplexer. This device has two independent decoders, each accepting two binary weighted inputs (A0n, A1n) and providing four mutually exclusive active-Low outputs ( $\overline{Q}0n-\overline{Q}3n$ ). Each decoder has an active-Low Enable ( $\overline{E}$ ). When  $\overline{E}$  is High, every output is forced High. The Enable can be used as the Data input for a 1-of-4 demultiplexer application.

	TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
I	74F139	5.3ns	13mA

#### **PIN CONFIGURATION**



### **ORDERING INFORMATION**

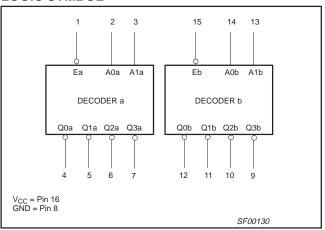
DESCRIPTION	COMMERCIAL RANGE $V_{CC}$ = 5V $\pm 10\%$ , $T_{amb}$ = 0°C to +70°C	PKG DWG#		
16-pin plastic DIP	N74F139N	SOT38-4		
16-pin plastic SO	N74F139D	SOT109-1		

#### INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

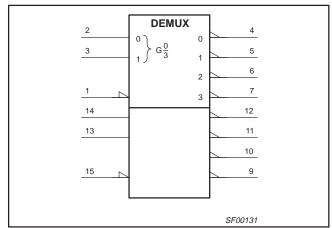
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW		
Ana, Anb	Address inputs	1.0/1.0	20μA/0.6mA		
Ēa, Ēb	Enable inputs (active Low)	1.0/1.0	20μA/0.6mA		
Q0n−Q3n	Data outputs (active Low)	50/33	1.0mA/20mA		

NOTE: One (1.0) FAST unit load is defined as: 20μA in the High state and 0.6mA in the Low state.

#### LOGIC SYMBOL

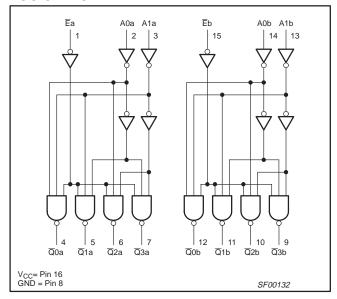


#### **IEC/IEEE SYMBOL**



74F139

### **LOGIC DIAGRAM**



### **FUNCTION TABLE**

	INPUTS		OUTPUTS					
Ē	A0	<b>A</b> 1	Q0	Q1	Q2	Q3		
Н	Х	Х	Н	Н	Н	Н		
L	L	L	L	Н	Н	Н		
L	Н	L	Н	L	Н	Н		
L	L	Н	Н	Н	L	Н		
L	Н	Н	Н	Н	Н	L		

#### NOTES:

H = High voltage level
L = Low voltage level
X = Don't care

## **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT	
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V	
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V	
I <sub>IN</sub>	Input current	-30 to +5	mA	
V <sub>OUT</sub>	Voltage applied to output in High output state	−0.5 to +V <sub>CC</sub>	V	
l <sub>OUT</sub>	Current applied to output in Low output state	40	mA	
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C	
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C	

### **RECOMMENDED OPERATING CONDITIONS**

CVMDOL	PARAMETER		UNIT		
SYMBOL	PARAMETER	MIN	NOM	MAX	UNII
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage	2.0			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>IK</sub>	Input clamp current			-18	mA
I <sub>OH</sub>	High-level output current			-1	mA
I <sub>OL</sub>	Low-level output current			20	mA
T <sub>amb</sub>	Operating free-air temperature range	0		+70	°C

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#### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

CVMDOL	DADAMETED	TEST CONDITIO		UNIT			
SYMBOL	PARAMETER	TEST CONDITIO	MIN	TYP <sup>2</sup>	MAX	UNII	
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	Lligh lovel output valtege	$V_{CC} = MIN, V_{IL} = MAX$	±10%V <sub>CC</sub>	2.5			V
V <sub>OH</sub>	High-level output voltage	$V_{IH} = MIN, I_{OH} = MAX$	±5%V <sub>CC</sub>	2.7	3.4		V
V	Low level cutout veltage	$V_{CC} = MIN, V_{IL} = MAX$	±10%V <sub>CC</sub>		0.30	0.50	V
V <sub>OL</sub>	Low-level output voltage	V <sub>IH</sub> = MIN, I <sub>OL</sub> = MAX	±5%V <sub>CC</sub>		0.30	0.50	V
V <sub>IK</sub>	Input clamp voltage	$V_{CC} = MIN, I_I = I_{IK}$			-0.73	-1.2	V
I <sub>I</sub>	Input current at maximum input voltage	$V_{CC} = MAX, V_I = 7.0V$				100	μΑ
I <sub>IH</sub>	High-level input current	$V_{CC} = MAX, V_I = 2.7V$				20	μА
I <sub>ILL</sub>	Low-level input current	$V_{CC} = MAX, V_I = 0.5V$				-0.6	mA
los	Short-circuit output current <sup>3</sup>	$V_{CC} = MAX$		-60		-150	mA
Icc	Supply current (total)	$V_{CC} = MAX$			13	20	mA

#### NOTES:

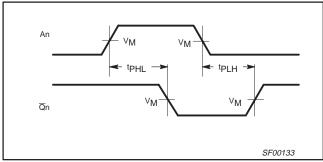
- 1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
   Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, IOS tests should be performed last.

#### AC ELECTRICAL CHARACTERISTICS

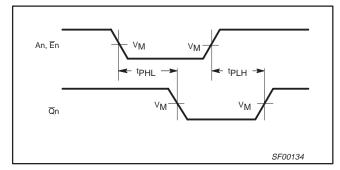
SYMBOL	PARAMETER	TEST CONDITION	Ta	CC = +5.0 1mb = +25 60pF, R <sub>L</sub> =	C	V <sub>CC</sub> = +5. T <sub>amb</sub> = 0°0 C <sub>L</sub> = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay A0 ir A1 to Qna, Qnb	Waveform 1, 2	3.5 4.0	5.3 6.1	7.0 8.0	3.0 4.0	8.0 9.0	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay En to Qna, Qnb	Waveform 2	3.5 3.0	5.4 4.7	7.0 6.5	3.5 3.0	8.0 7.5	ns

### **AC WAVEFORMS**

For all waveforms,  $V_M = 1.5V$ 



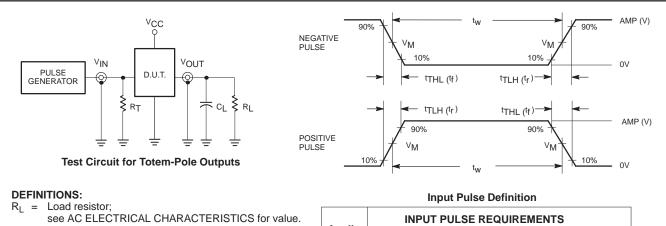
Waveform 1. Propagation Delay for Inverting Outputs



Waveform 2. Propagation Delay for Non-Inverting Outputs

74F139

### **TEST CIRCUIT AND WAVEFORMS**



 $C_L = Load$  capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.

Termination resistance should be equal to Z<sub>OUT</sub> of pulse generators.

ı	INP	UT PU	LSE REQU	REMEN	TS	

family	INPUT FULSE REQUIREMENTS										
family	amplitude	$V_{\text{M}}$	rep. rate	t <sub>w</sub>	t <sub>TLH</sub>	t <sub>THL</sub>					
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns					

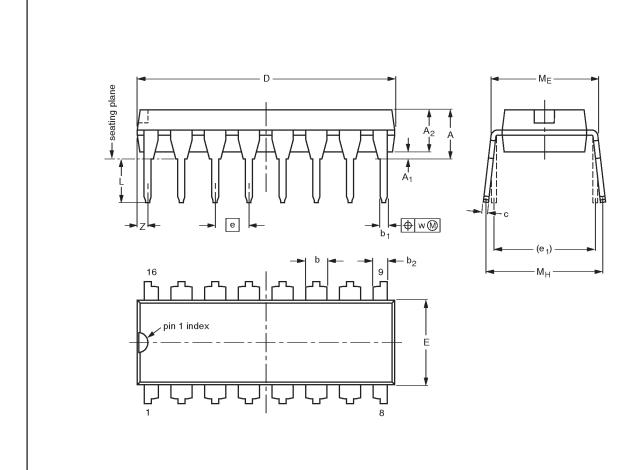
SF00006

# Dual 1-of-4 decoder/demultiplexer

74F139

# DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	b <sub>2</sub>	C	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

scale

10 mm

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE	OUTLINE VERSION         REFERENCES           JEC         JEDEC         EIAJ	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT38-4				□ •	<del>92-11-17</del> 95-01-14

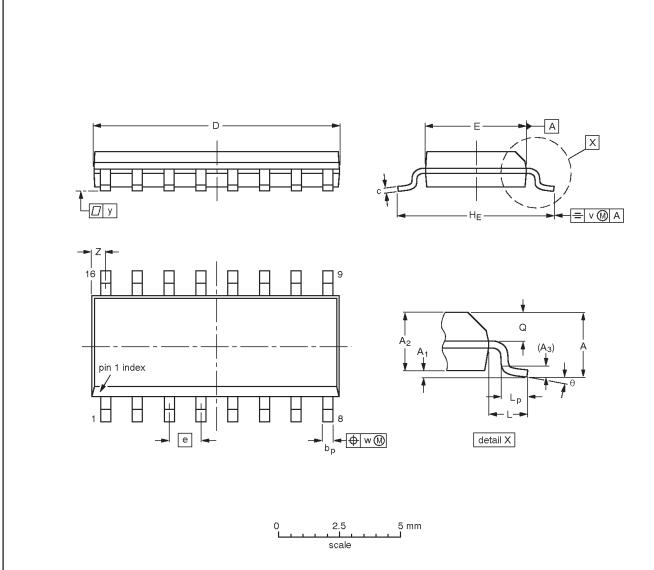
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# Dual 1-of-4 decoder/demultiplexer

74F139

# SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



# DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	1330E DATE
SOT109-1	076E07S	MS-012AC			<del>95-01-23</del> 97-05-22

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# Dual 1-of-4 decoder/demultiplexer

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#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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